SHARP GP2W0116YPS

(T _250C)

GP2W0116YPS

■ Features

- 1. Compliant with IrDA1.2 low power
- 2. Integrated package of transmitter/receiver. (7.2×2.75×height 1.85mm)
- 3. General purpose
- Low dissipation current due to shut-down function (Dissipation current at shut-down mode:Max. 0.1μA)
- 5. Soldering reflow type
- 6. Shield type

■ Applications

- 1. Cellular phones, PHS
- 2. Personal information tools

■ Absolute Maximum Ratings

Absolute Maximum Natings (1a=25°C)					
Parameter	Symbol	Rating	Unit		
Supply voltage	V_{CC}	0 to 6.0	V		
LED Supply voltage	V_{LEDA}	0 to 7.0	V		
*1 Peak forward current	I_{FM}	60	mA		
Operating temperature	T_{opr}	-40 to +85	°C		
Storage temperature	T_{stg}	-40 to +85	°C		
*2 Soldering temperature	T_{sol}	260	°C		

^{*1} Pulse width 78.1µs, Duty ratio:3/16

■ Recommended Operating Conditions

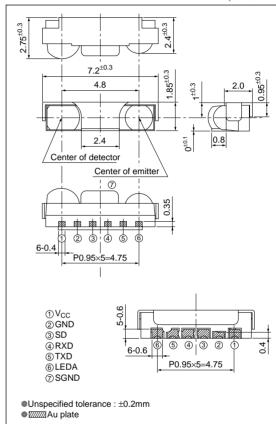
Parameter	Symbol	Rating	Unit
Supply voltage	V_{CC}	2.0 to 3.6	V
LED Supply voltage	V_{LEDA}	2.0 to 6.0	V
Transmission rate	BR	2.4 to 115.2	kb/s
High level input voltage (SD terminal)	V_{IHSD}	V _{CC} ×0.67 to V _{CC}	V
Low level input voltage (SD terminal)	V_{ILSD}	0 to V _{CC} ×0.1	V
*3 High level input voltage (TXD)	V_{IHTXD}	$V_{CC} \times 0.8$ to V_{CC}	V
*3 Low level input voltage (TXD)	V_{ILTXD}	0 to V _{CC} ×0.2	V

^{*3} Refer to Fig.9

IrDA Transceiver Module Compliant with IrDA1.2 Low Power

■ Outline Dimensions

(Unit: mm)



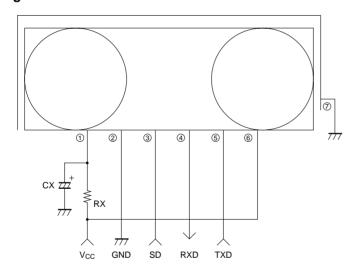
^{*2} For MAX. 10s

■ Electro-optical	Characteristics
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	■ Electro-optical Characteristics (T _a =25°C, V _{CC} =3.3						$V_{CC} = 3.3V$)
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Dissipation current at no input signal	I_{CC}	No input light, output terminal open, V _{IHSD} =0V	ı	90	120	μΑ
	S/D dissipation current	$I_{\text{CC-S}}$	No input light, output terminal open, $V_{IHSD} = V_{CC}$	-	0.001	0.1	μΑ
side	High level output voltage	V_{OH}	I_{OH} =-200 μ A, V_{CC} =2.0 to 3.6V *4	V _{CC} -0.4	_	-	V
	Low level output voltage	V_{OL}	I_{OL} =200 μ A, V_{CC} =2.0 to 3.6V *4	İ	_	0.45	V
Receiver	Low level pules width	$t_{\rm w}$	BR=115.2kb/s, \$\phi\$15°, C _L =10pF *4	1.28	-	6.0	μs
Rec	Rise time	t_r	BR=115.2kb/s, φ≤15°, C _L =10pF *4	_	_	0.06	μs
	Fall time	$t_{\rm f}$	BR=115.2kb/s, ϕ ≤15°, C _L =10pF *4	1	-	0.06	μs
	Maximum communication distance	L	BR=115.2kb/s, φ≤15° *4	21	_	-	cm
Transmitter side	Radiant intensity	$I_{\rm E}$	DD 445 011 / 1450 TV 0 071 *5	4.0	_	25	mW/sr
	Peak emission wavelength	λ_{p}	BR=115.2kb/s, \$\phi \le 15\circ\$, \$V_{IHTXD}=2.8V *5\$	850	870	900	nm

^{*4} Refer to Fig.4, 5, 6

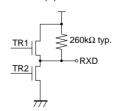
Fig.1 Recommended External Circuit



*I/O Logic table

SD	TXD	LED	Receiver	TR1	TR2	RXD
	High	ON	Don't care	-	-	Not valid
Low	Low	OFF	IrDA signal	OFF	ON	Low
	LOW	OFF	No signal	ON	OFF	Low High
High	Don't care	OFF	Don't care	OFF	OFF	Pull-up

*RXD Equipment circuit



① V_{CC} ② GND ③ SD

⑤ TXD

6 LEDA 7 SGND

Components	Recommended values
CX	1μF/6.3V
RX	1 to 15Ω

(Note) Please choose the most suitable CX according to the noise level and noise frequency of power

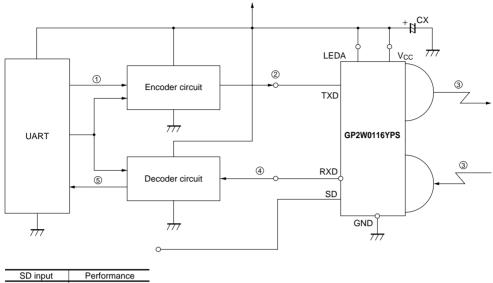
> Depend on noise level and noise frequency of power supply, CX does not work well.

There are cases that some pulse noises from RXD other than signal will occur in certain communication area. Please check by finish product that there are no problem at all communication area and data

If there are any problem, please check by inserting RX (1 to 15Ω) in the circuit drawing.

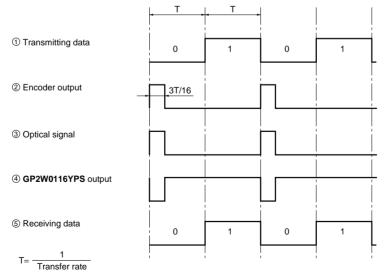
^{*5} Refer to Fig.7, 8, 9

Fig.2 System Configuration



	SD input	Performance	
Low		Normal mode	
	High	Shut down mode	

Fig.3 Example of Signal Waveform



Transfer rate; 2.4kb/s,9.6kb/s,19.2kb/s,38.4kb/s,57.6kb/s,115.2kb/s

Fig.4 Input Signal Waveforrm (Receiver side)

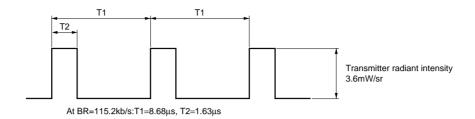


Fig.5 Output Waveform Specification (Receiver side)

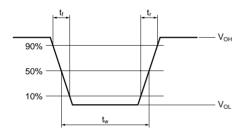
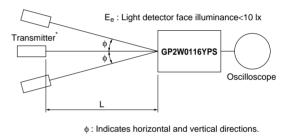


Fig.6 Standard Optical System (Receiver side)



* Transmitter shall use **GP2W0116YPS** (\(\lambda\)p=870nm TYP.) which is adjusted the radiation intensity at 3.6mW/sr

Fig.7 Output Waveform Specification (Transmitter side)

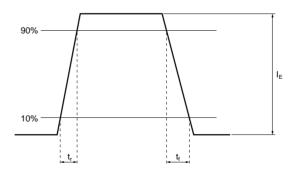


Fig.8 Standard Optical System (Transmitter side)

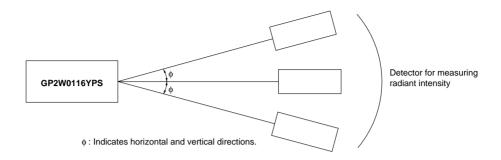


Fig.9 Recommended Circuit of Transmitter side

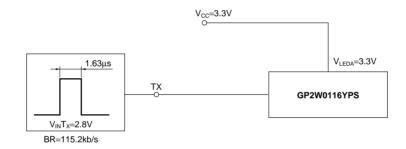
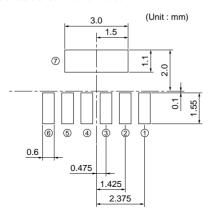


Fig.10 Recommended PCB Foot Pattern

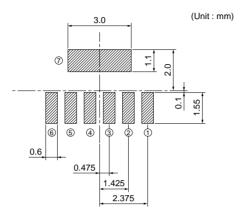
Dimensions are shown for reference



	Terminal	Symbol
1	Supply voltage	V _{CC}
2	Ground	GND
3	Shutdown	SD
4	Receiver data output	RXD
⑤	Transmitter data input	TXD
6	LED anode	LEDA
7	Shield ground	SGND

Fig.11 Recommended Size of Solder Paste (Reference)

Please open the solder mask as below so that the size of solder paste for this device before reflow soldering must be as large as one of the foot pattern land indicated Fig.10



Solder paste area

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